MICROWAVE POWER GaAs FET

Internally Matched Power GaAs FETs (X, Ku-Band)

Features

- High power
 - $P_{1dB} = 33.5 \text{ dBm}$ at 14.0 GHz to 14.5 GHz
- High gain
 - $G_{1dB} = 6.5 dB$ at 14.0 GHz to 14.5 GHz
- Broadband internally matched
- · Hermetically sealed package

RF Performance Specifications (T_a = 25°C)

Characteristic	Symbol	Condition	Unit	Min.	Тур.	Max
Output Power at 1dB Compression Point	P _{1dB}	V _{DS} = 9V - f = 14.0 - 14.5 GHz	dBm	32.5	33.5	-
Power Gain at 1dB Compression Point	G _{1dB}		dB	5.5	6.5	-
Drain Current	I _{DS}		Α	-	0.85	1.1
Power Added Efficiency	$\eta_{\sf add}$		%	-	23	-
Channel-Temperature Rise	ΔT_ch	V _{DS} x I _{DS} x R _{th (c-c)}	°C	-	-	60

Electrical Characteristics (T_a = 25°C)

Characteristic	Symbol	Condition	Unit	Min.	Тур.	Max.
Transconductance	gm	V _{DS} = 3V I _{DS} = 1.0A	mS	-	600	_
Pinch-off Voltage	V _{GSoff}	V _{DS} = 3V I _{DS} = 30 mA	V	-2	-3.5	-5
Saturated Drain Current	I _{DSS}	V _{DS} = 3V V _{GS} = 0V	Α	-	2.0	2.6
Gate-Source Breakdown Voltage	V _{GSO}	I _{GS} = -30 μA	٧	-5	-	-
Thermal Resistance	R _{th (c-c)}	Channel to Case	°C/W	-	5	6

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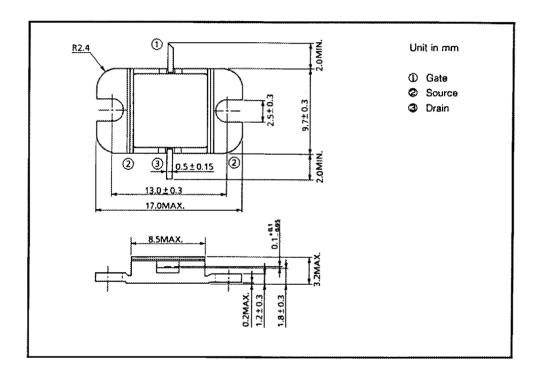
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The information contained here is subject to change without notice.

Absolute Maximum Ratings ($T_a = 25$ °C)

Characteristic	Symbol	Unit	Rating
Drain-Source Voltage	V _{DS}	V	15
Gate-Source Voltage	V _{GS}	V	-5
Drain Current	I _D	Α	2.6
Total Power Dissipation (T _c = 25°C)	P _T	W	15
Channel Temperature	T _{ch}	°C	175
Storage Temperature	T _{stg}	ç	-65 ~ 175

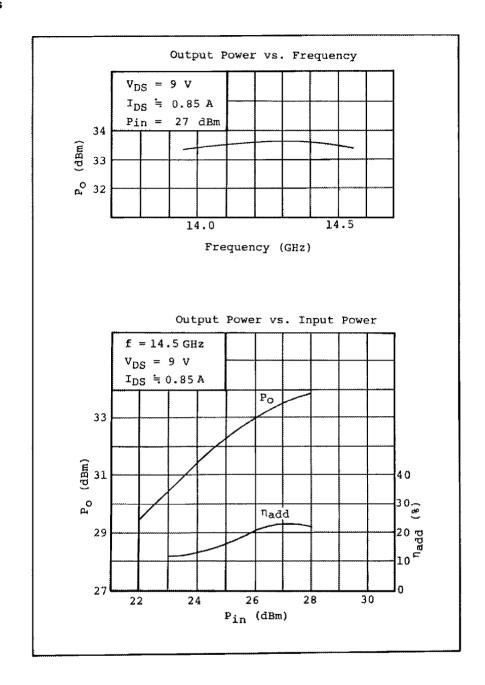
Package Outline (2-9D1B)



Handling Precautions for Packaged Type

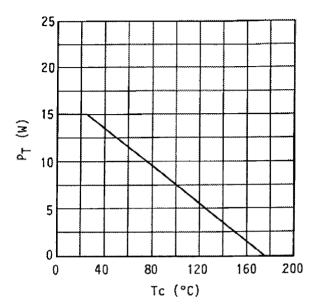
Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

RF Performances



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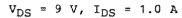
Power Dissipation vs. Case Temperature

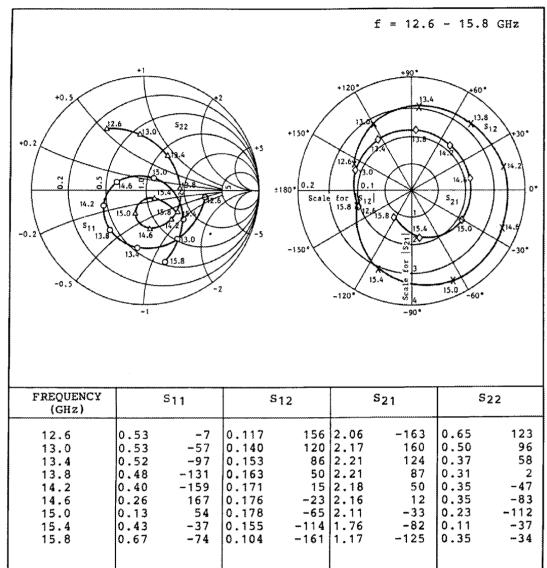


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TIM1414-2 S-Parameters (Magn. and Angles)





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